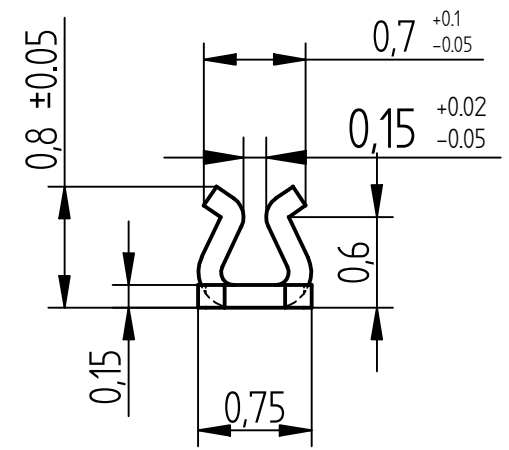
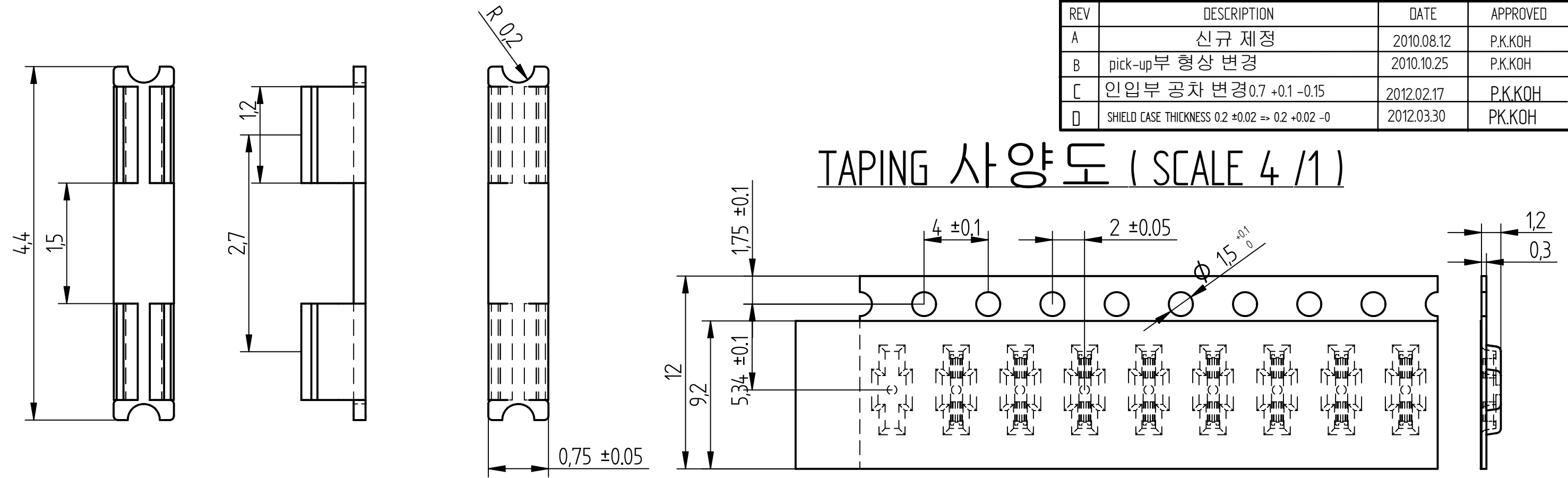


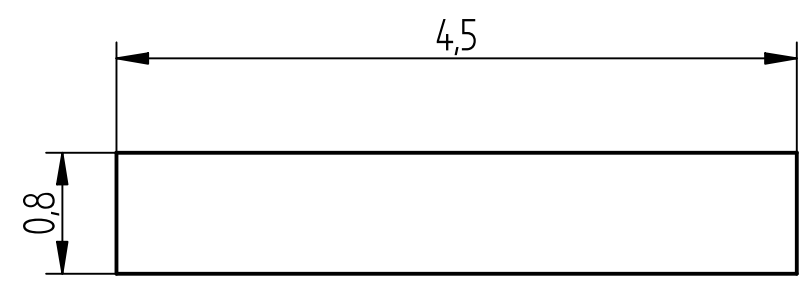
REVISION HISTORY

REV	DESCRIPTION	DATE	APPROVED
A	신규 제정	2010.08.12	P.K.KOH
B	pick-up부 형상 변경	2010.10.25	P.K.KOH
C	인입부 공차 변경 0.7 +0.1 -0.15	2012.02.17	P.K.KOH
D	SHIELD CASE THICKNESS 0.2 ±0.02 => 0.2 +0.02 -0	2012.03.30	PK.KOH

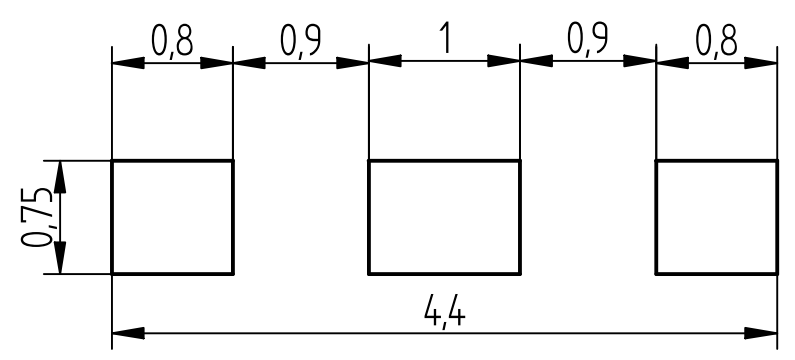
TAPING 사양도 (SCALE 4/1)



SCALE 20/1



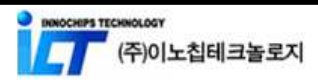
RECOMMENDED PCB LAYOUT



RECOMMENDED STENCIL LAYOUT

NOTES

- MATERIAL : SUS301
- MATERIAL THICKNESS : 0.15t
- FINISHED : Sn(100%) PLATING ON BOTH SIDE
(Ni 0.5 μ m Sn 1.27 μ m)
- PACKING MATERIALS.
- REEL : HIPS 0.3t
- COVER TAPE : PS
- Q'TY/REEL : 10,000ea
- AVAILABLE SHIELD CASE THICKNESS : 0.2 +0.02 -0
- CONTACT RESISTANCE : MAX 300m Ω
- STENCIL THICKNESS : 0.12T
- Maintain 90° ± 3 while engage & disengage shield can & shield clip to prevent deformation & to maintain retention force of shield clip

DATA	NAME	 (주)이노칩테크놀로지 Solution Provider	
APP. 2010.08.12	LEE		
CHECK		TITLE SHIELD CLIP	
DESIG. 2010.08.12	P.K.KO	SIZE A3	DWG NO IC SRC-4408 SFR
UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN MILLIMETERS TOLERANCES ARE ANGLES ± 0.3° 0 ~ 1 ± 0.05 1 ~ 5 ± 0.1 5 ~ 10 ± 0.15		REV D	FILE NAME: IC SRC-4408SFR.dft
		SCALE:	WEIGHT: